

IN THE CLAIMS

Claims 1-276. (canceled)

277. (new) Apparatus for placement in a patient, comprising:

 circuitry, which is adapted to be placed in the patient;

 a lead wire; and

 an electrically-conductive connector, which is soldered to the circuitry and which is mechanically coupled to the lead wire so as to be electrically coupled thereto.

278. (new) The apparatus according to claim 277, wherein the connector is crimped to the lead wire, so as to be mechanically coupled thereto.

279. (new) The apparatus according to claim 278, wherein the connector comprises a hollow tube, wherein a portion of the lead wire is disposed within the hollow tube, and wherein the hollow tube is crimped to the portion of the lead wire.

280. (new) The apparatus according to claim 277, wherein the lead wire comprises MP35N.

281. (new) The apparatus according to claim 277, wherein the lead wire comprises platinum/iridium.

282. (new) The apparatus according to claim 277, wherein the lead wire comprises 1-60% iron by weight.

283. (new) The apparatus according to claim 277, wherein the lead wire comprises 1-40% iron by weight.

284. (new) The apparatus according to claim 277, wherein the lead wire comprises 1-20% iron by weight.

285. (new) The apparatus according to claim 277, wherein the connector is coated with gold.

286. (new) The apparatus according to claim 277, wherein the connector has been treated with phosphoric acid.

287. (new) The apparatus according to claim 277, wherein the circuitry is adapted to be implanted in the patient.

288. (new) The apparatus according to claim 277, wherein the circuitry is adapted to be incorporated in a catheter.
289. (new) The apparatus according to claim 277, wherein the lead wire comprises a silver core.
290. (new) The apparatus according to claim 277, wherein the connector comprises stainless steel.
291. (new) The apparatus according to claim 277, wherein the circuitry comprises a sensor.
292. (new) The apparatus according to claim 291, wherein the sensor comprises a pressure sensor.
293. (new) The apparatus according to claim 291, wherein the sensor comprises a chemical sensor.
294. (new) The apparatus according to claim 291, wherein the sensor comprises an electrode, adapted to sense electrical activity in tissue of the patient where the apparatus is placed.
295. (new) The apparatus according to claim 291, wherein the sensor comprises a temperature sensor.
296. (new) The apparatus according to claim 291, wherein the sensor comprises a flow sensor, adapted to sense a flow of blood in a vicinity of the apparatus.
297. (new) The apparatus according to claim 277, wherein the circuitry comprises an active element.
298. (new) The apparatus according to claim 297, wherein the active element comprises a stimulating electrode.
299. (new) The apparatus according to claim 297, wherein the active element comprises a light source adapted to facilitate photodynamic therapy.
300. (new) The apparatus according to claim 297, wherein the active element comprises an electroactive polymer.
301. (new) The apparatus according to claim 297, wherein the active element comprises a mechanical actuator.

302. (new) A method comprising:

mechanically coupling an electrically-conductive connector to a lead wire so that the connector is electrically coupled to the lead wire;
soldering the connector to circuitry; and
placing the circuitry in a patient.

303. (new) The method according to claim 302, wherein mechanically coupling the connector to the lead wire comprises crimping the connector to the lead wire.

304. (new) The method according to claim 303, wherein the connector includes a hollow tube, and wherein crimping the connector comprises disposing a portion of the lead wire within the hollow tube, and crimping the hollow tube to the portion of the lead wire.

305. (new) The method according to claim 302, wherein the lead wire comprises MP35N, and wherein mechanically coupling the connector comprises mechanically coupling the connector to the MP35N lead wire.

306. (new) The method according to claim 302, wherein the lead wire comprises platinum/iridium, and wherein mechanically coupling the connector comprises mechanically coupling the connector to the platinum/iridium lead wire.

307. (new) The method according to claim 302, wherein the lead wire comprises 1-60% iron by weight, and wherein mechanically coupling the connector comprises mechanically coupling the connector to the 1-60% iron lead wire.

308. (new) The method according to claim 302, wherein the lead wire comprises 1-40% iron by weight, and wherein mechanically coupling the connector comprises mechanically coupling the connector to the 1-40% iron lead wire.

309. (new) The method according to claim 302, wherein the lead wire comprises 1-20% iron by weight, and wherein mechanically coupling the connector comprises mechanically coupling the connector to the 1-20% iron lead wire.

310. (new) The method according to claim 302, wherein soldering the connector comprises coating the connector with gold.

311. (new) The method according to claim 302, wherein soldering the connector comprises treating the connector with phosphoric acid.

312. (new) The method according to claim 302, wherein placing the circuitry in the patient comprises implanting the circuitry in the patient.

313. (new) The method according to claim 302, wherein placing the circuitry in the patient comprises incorporating the circuitry in a catheter.

314. (new) The method according to claim 302, wherein the lead wire comprises a silver core, and wherein mechanically coupling the connector comprises mechanically coupling the connector to the lead wire comprising the silver core.

315. (new) The method according to claim 302, wherein the connector comprises stainless steel, and wherein mechanically coupling the connector comprises mechanically coupling the stainless steel connector.